

959T

Low-Solids No-Clean Flux Pen[®]

For Lead-bearing and Lead-free alloys

Product Description

Kester 959T is a no-clean, non-corrosive, halide free Flux Pen[®] that is specifically designed for lead-free rework of conventional and surface mount circuit board assemblies. Essentially no residue remains after soldering. Kester 959T was developed with a modified surface tension to aid in soldering boards that have surface mount and high component densities. This comprehensive formulation possesses improved wetting characteristics and also exhibits superior corrosion inhibiting properties and provides a non-tacky residue. A major advantage of this flux is the reduced odor associated with the soldering process. Kester 959T incorporates a small amount of rosin for higher reliability.

Performance Characteristics:

- Residues almost colorless
- Improves soldering performance
- Reduced odor associated with soldering process
- Eliminates the need and expense of cleaning
- Non-corrosive tack-free residues
- Contains < 0.5% Rosin
- Classified as ORL0 per J-STD-004
- Compliant to Bellcore GR-78

RoHS Compliance

This product meets the requirements of the RoHS (Restriction of Hazardous Substances) Directive, 2002/95/EC Article 4 for the stated banned substances.

Physical Properties

Specific Gravity: 0.794 ± 0.005

Antoine Paar DMA 35 @ 25°C

Percent Solids (typical): 2.9

Tested to J-STD-004, IPC-TM-650, Method 2.3.34

Acid Number (typical): 21.0 mg KOH/g of flux

Tested to J-STD-004, IPC-TM-650, Method 2.3.13

pH (10% solution): 3.0

Hanna Instruments 8314 @ 25°C

Reliability Properties

Copper Mirror Corrosion: Low

Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Corrosion Test: Low

Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Silver Chromate: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Chloride and Bromides: None Detected

Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Fluorides by Spot Test: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

SIR, IPC (typical): Pass

Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

	Blank	959T
Day 1	7.9 × 10 ⁹ Ω	1.6 × 10 ⁹ Ω
Day 4	8.4 × 10 ⁹ Ω	1.9 × 10 ⁹ Ω
Day 7	7.4 × 10 ⁹ Ω	1.9 × 10 ⁹ Ω

Application Notes

Flux Application:

Kester 959T is applied to circuit boards via Flux Pen® for rework of printed wire assemblies.

Process Considerations:

Kester 959T should only be applied to areas that will be fully heated by the soldering iron or other reflow tool. Care should be taken to avoid flooding the assembly. The surface tension has been adjusted to help the flux form a thin film on the board surface allowing rapid solvent evaporation.

Cleaning:

Kester 959T flux residues are non-conductive, non-corrosive and do not require removal in most applications.

Storage and Shelf Life:

Kester 959T is flammable. Store away from sources of ignition. Shelf life is 2 years from date of manufacture when handled properly and held at 10-25°C (50-77°F).

Health & Safety:

This product, during handling or use, may be hazardous to health or the environment. Read the Material Safety Data Sheet and warning label before using this product.

World Headquarters: 800 W. Thorndale Avenue, Itasca, Illinois, 60143 USA

Phone: (+1) 847-297-1600 • **Email:** customerservice@kester.com • **Website:** www.kester.com

Asia Pacific Headquarters

500 Chai Chee Lane
Singapore 469024
(+65) 6449-1133
customerservice@kester.com.sg

European Headquarters

Zum Plom 5
08541 Neuensalz
Germany
(+49) 3741 4233-0
customerservice@kester-eu.com

Japanese Headquarters

20-11 Yokokawau 2-Chome
Sumida-Ku
Tokyo 130-0003 Japan
(+81) 3-3624-5351
jpsales@kester.com.sg

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